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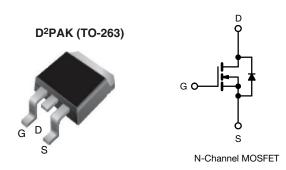
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

EF Series Power MOSFET With Fast Body Diode



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.) at T _J max. 650			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.088		
Q _g max. (nC)	53			
Q _{gs} (nC)	12			
Q _{gd} (nC)	11			
Configuration	Single			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION				
Package	D ² PAK (TO-263)			
Lead (Pb)-free and halogen-free	SiHB105N60EF-GE3			

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600	V	
Gate-source voltage			V_{GS}	± 30	7 v	
Continuous drain current (T, _I = 150 °C)	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	C I _D	29	А	
Continuous drain current (1 J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C		19		
Pulsed drain current ^a			I _{DM}	73	I	
Linear derating factor				1.67	W/°C	
Single pulse avalanche energy b			E _{AS}	226	mJ	
Maximum power dissipation			P _D	208	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope T _J = 125 °C		dv/dt	70	V/ns		
Reverse diode dv/dt ^d			50) v/ns		
Soldering recommendations (peak temperature) c For 10 s				260	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 4 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 400 A/ μ s, starting T_J = 25 °C



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THERMAL RESISTANCE RATINGS						
PARAMETER SYMBOL TYP. MAX. UNIT						
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W		
Maximum junction-to-case (drain)	R_{thJC}	-	0.6	C/VV		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.63	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	3	-	5	V
Osta a superiori de la constanta de la constan		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA
Zana anta malta an aluain annuant		V _{DS} = 480 V, V _{GS} = 0 V		-	-	1	μA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	2	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 13 A	-	0.088	0.102	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 20 V, I _D = 13 A	-	8	-	S
Dynamic							
Input capacitance	C _{iss}		$V_{GS} = 0 V$,	-	1804	-	
Output capacitance	C _{oss}	,	V _{DS} = 100 V,	-	82	-	•
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	6	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	63	-	pF
Effective output capacitance, time related ^b	C _{o(tr)}			-	407	-	
Total gate charge	Qg			-	35	53	
Gate-source charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 11 \text{ A}, V_{DS} = 480 \text{ V}$		-	12	-	nC
Gate-drain charge	Q_{gd}			-	11	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 13 A,		-	20	40	
Rise time	t _r			-	28	56	
Turn-off delay time	t _{d(off)}	V _{GS} =	$= 10 \text{ V}, \text{ R}_{\text{g}} = 9.1 \Omega$	-	39	78	ns
Fall time	t _f	1		-	19	38	
Gate input resistance	R _g	f = 1 MHz, open drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	29	
Pulsed diode forward current	I _{SM}			-	-	73	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 13 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 13 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 400 \text{ V}$		-	125	250	ns
Reverse recovery charge	Q _{rr}			-	0.8	1.6	μC
Reverse recovery current	I _{RRM}			_	12	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

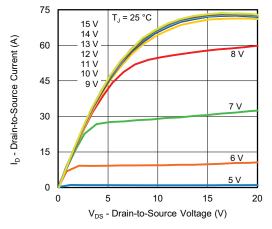


Fig. 1 - Typical Output Characteristics

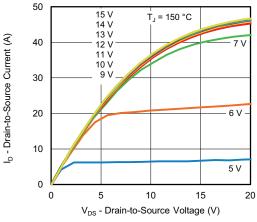


Fig. 2 - Typical Output Characteristics

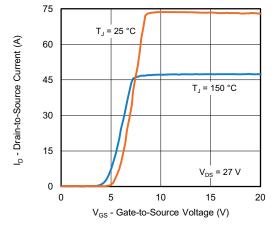


Fig. 3 - Typical Transfer Characteristics

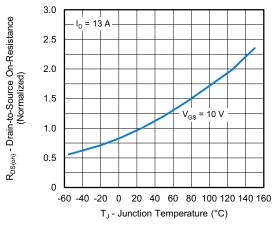


Fig. 4 - Normalized On-Resistance vs. Temperature

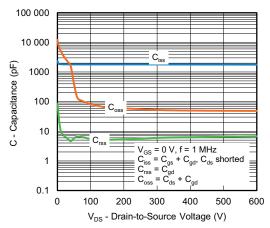


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

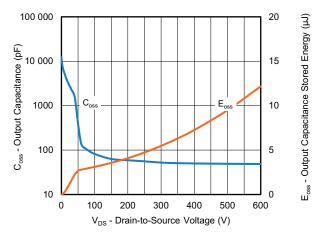


Fig. 6 - Coss and Eoss vs. VDS



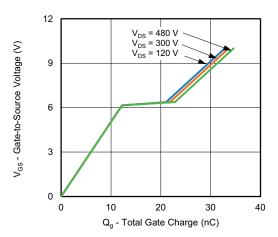


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

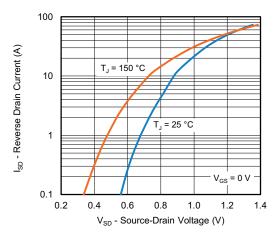


Fig. 8 - Typical Source-Drain Diode Forward Voltage

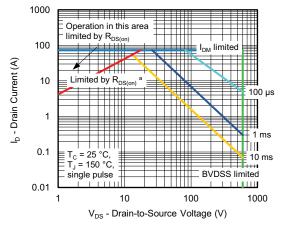


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

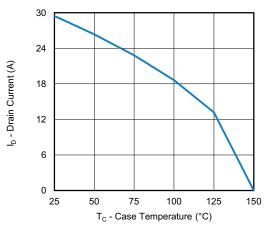


Fig. 10 - Maximum Drain Current vs. Case Temperature

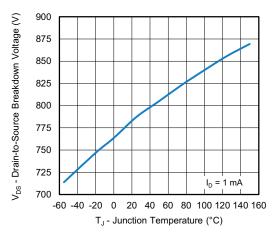


Fig. 11 - Temperature vs. Drain-to-Source Voltage



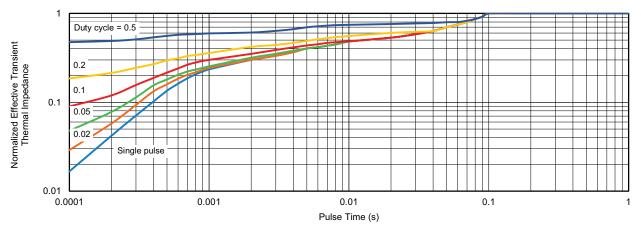


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

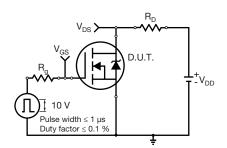


Fig. 13 - Switching Time Test Circuit

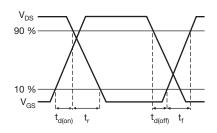


Fig. 14 - Switching Time Waveforms

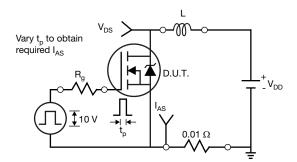


Fig. 15 - Unclamped Inductive Test Circuit

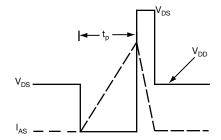


Fig. 16 - Unclamped Inductive Waveforms

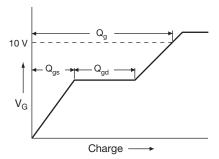


Fig. 17 - Basic Gate Charge Waveform

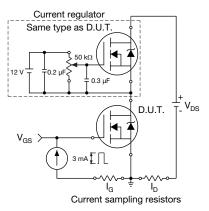
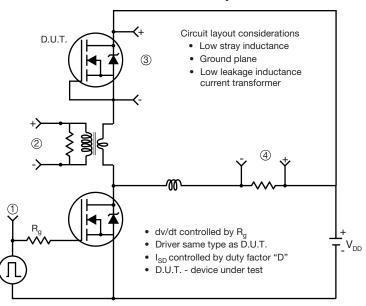


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



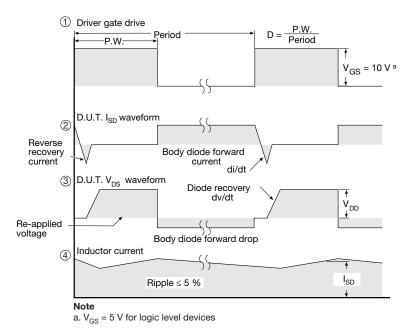


Fig. 19 - For N-Channel

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TO-263AB (HIGH VOLTAGE)







	MILLIN	METERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
С	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
Е	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	ı
е	2.54 BSC		0.100 BSC	
Н	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	ı	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010	BSC
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08

DWG: 5970

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
- 4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
- 5. Dimension b1 and c1 apply to base metal only.
- 6. Datum A and B to be determined at datum plane H.
- 7. Outline conforms to JEDEC outline to TO-263AB.

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RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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